

SOT1914-1

WLCSP56, wafer level chip scale package, 56 terminals, 0.4 mm pitch, 4.39 mm x 3.59 mm x 0.5 mm body

4 April 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP56
Package type industry code	WLCSP56
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-02-2018
Manufacturer package code	98ASA01184D

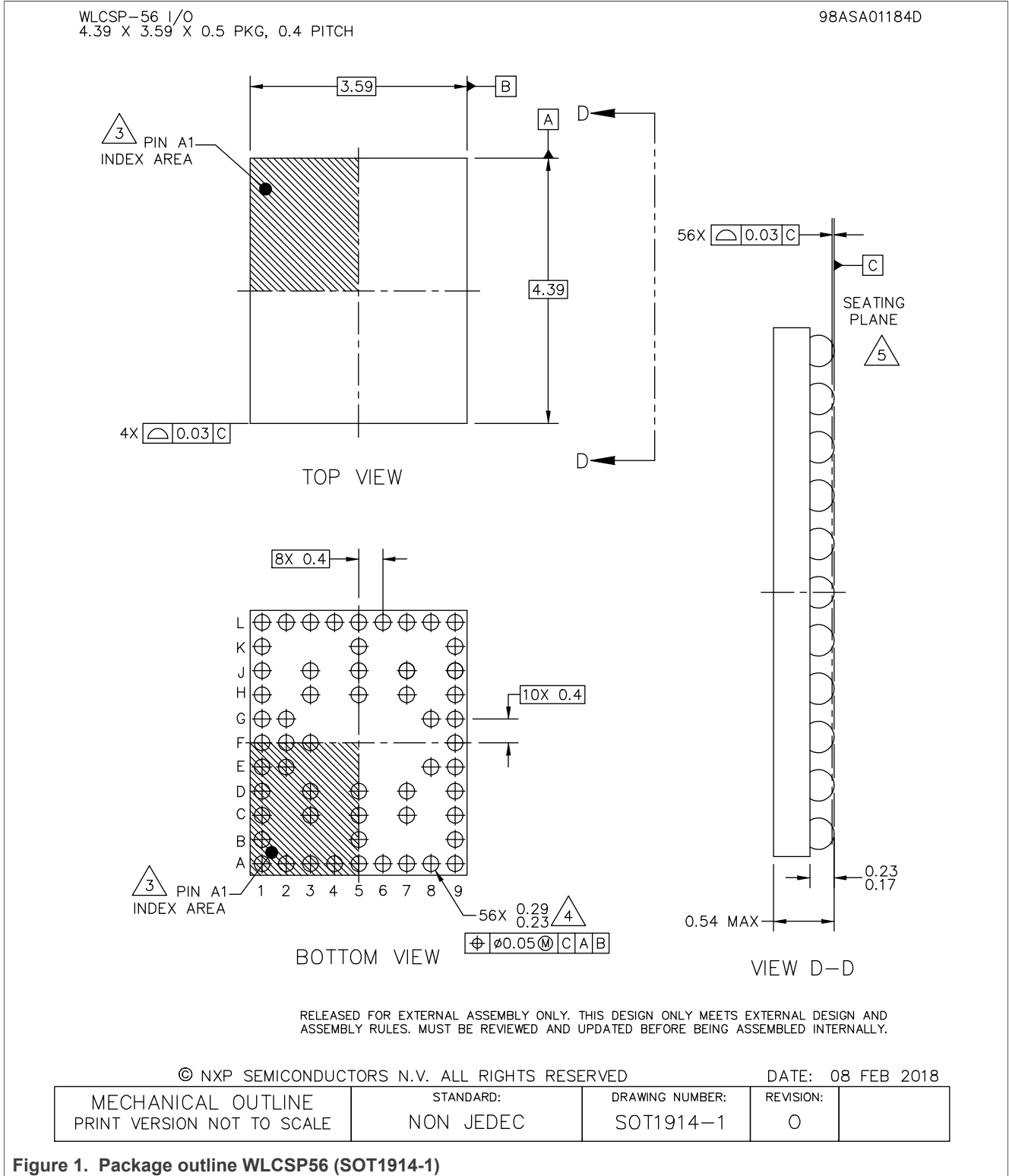
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.36	4.39	4.42	mm
package width	3.56	3.59	3.62	mm
seated height	-	0.5	0.54	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	56	-	



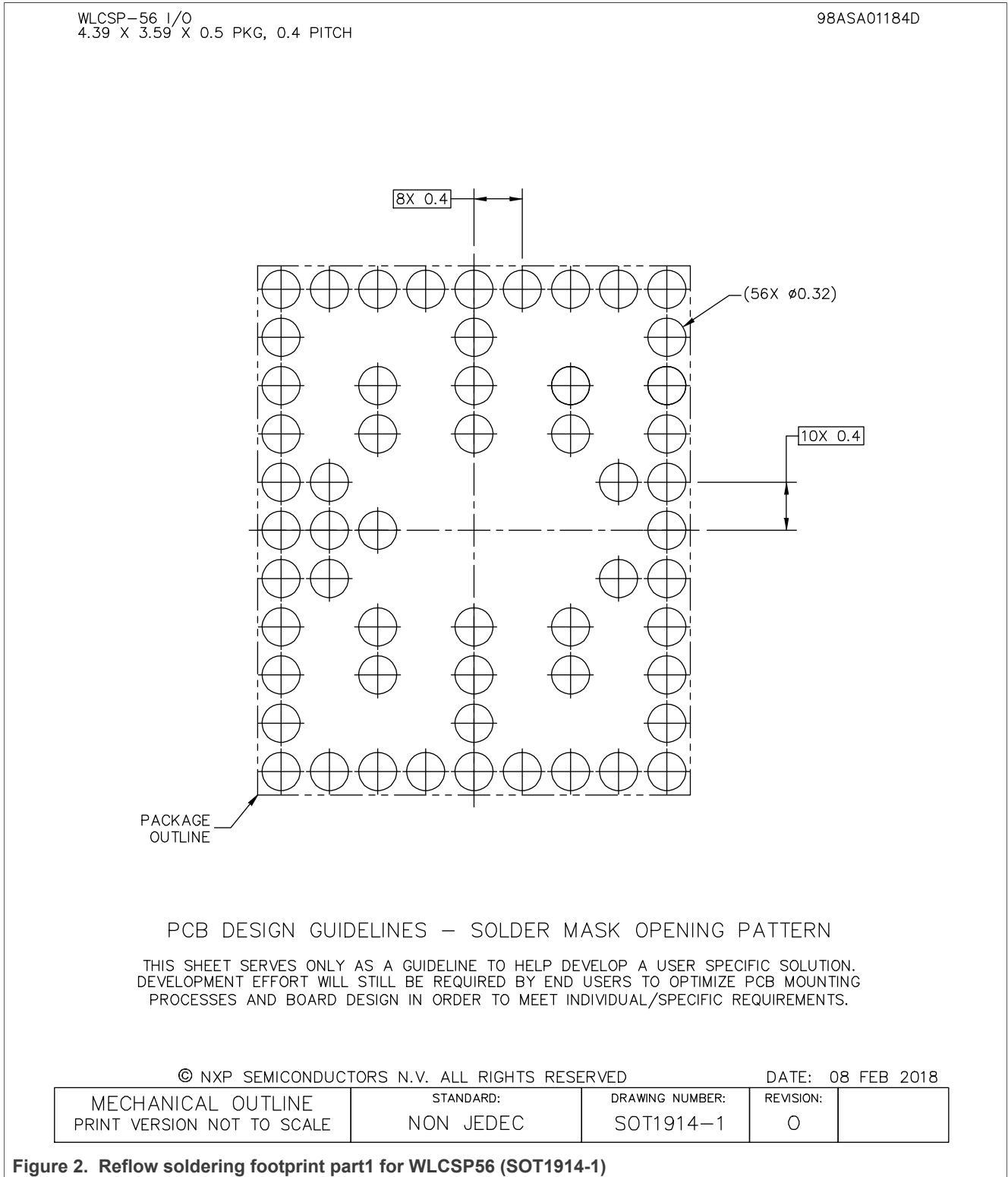
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2 Package outline



WLCSP56, wafer level chip scale package, 56 terminals, 0.4 mm pitch, 4.39 mm x 3.59 mm x 0.5 mm body

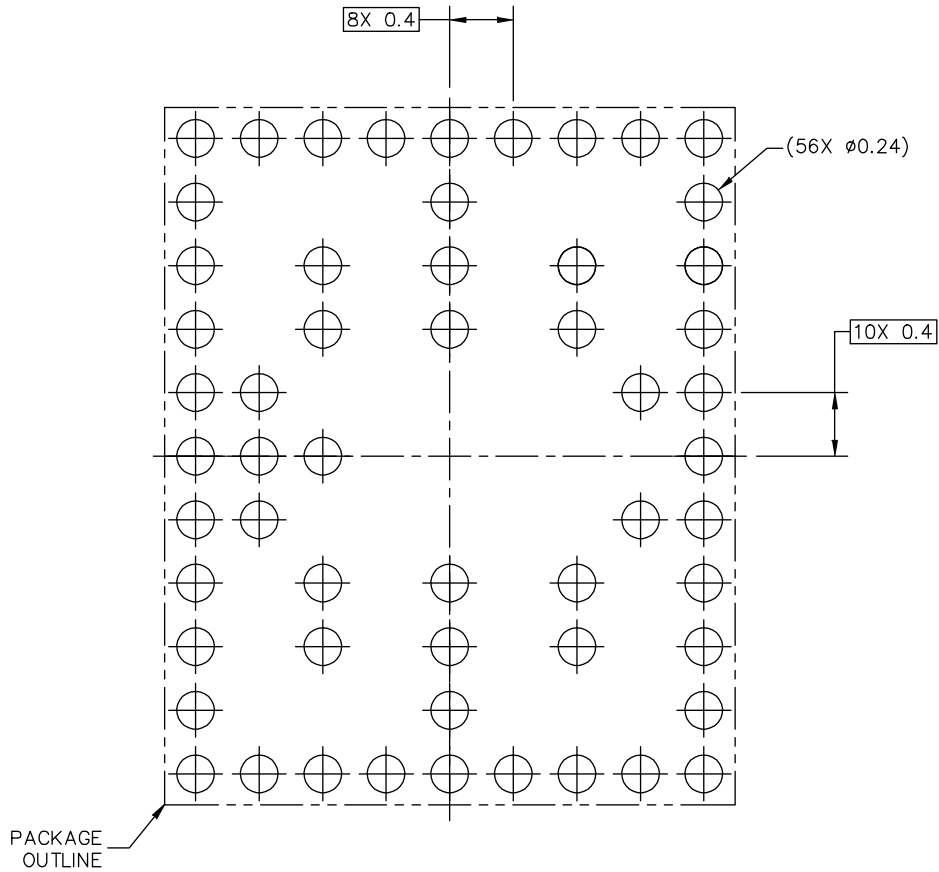
3 Soldering



WLCSP56, wafer level chip scale package, 56 terminals, 0.4 mm pitch, 4.39 mm x 3.59 mm x 0.5 mm body

WLCSP-56 I/O
4.39 X 3.59 X 0.5 PKG, 0.4 PITCH

98ASA01184D



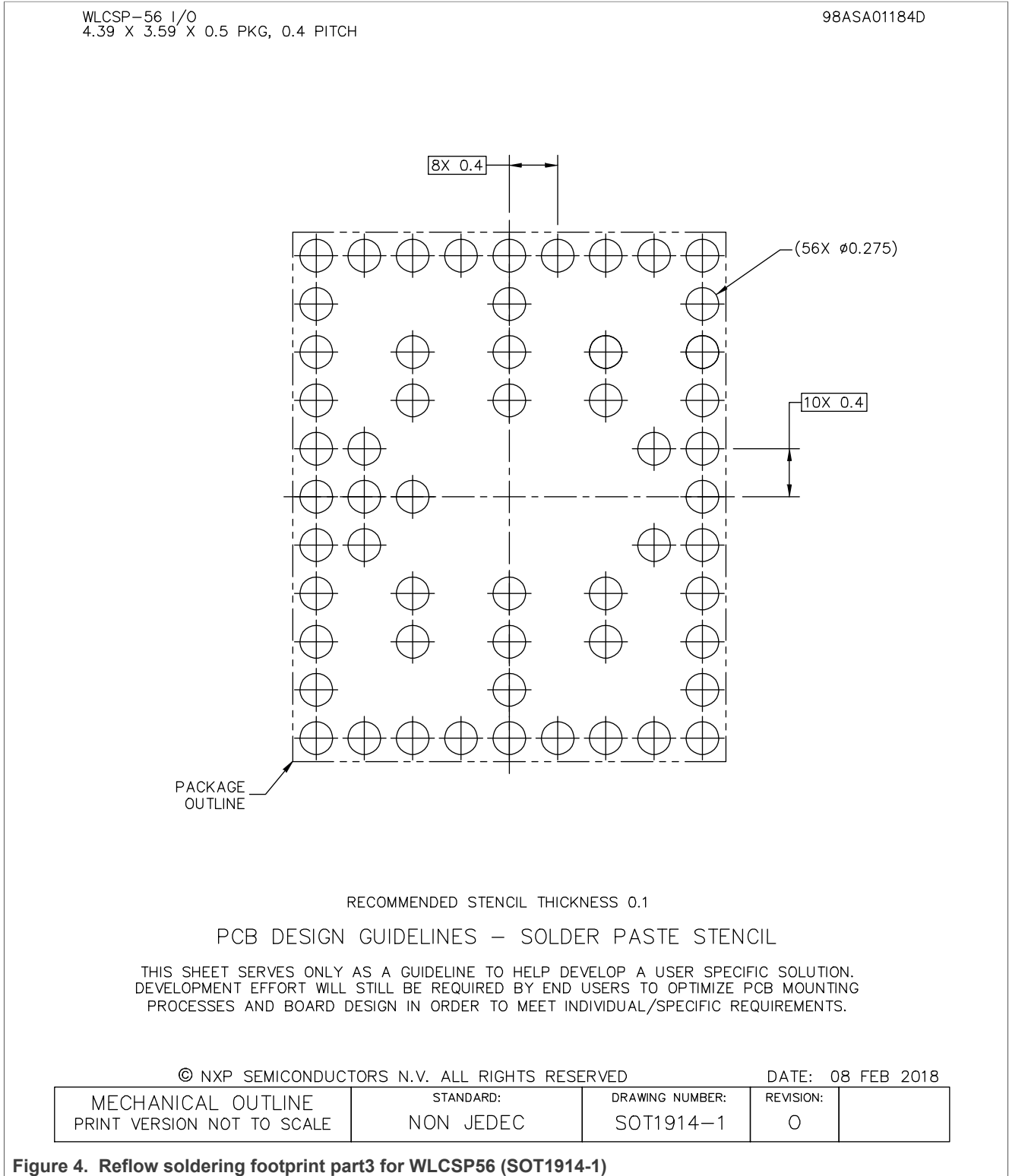
PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA
 THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
 DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
 PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1914-1	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for WLCSP56 (SOT1914-1)

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WLCSP-56 I/O
4.39 X 3.59 X 0.5 PKG, 0.4 PITCH

98ASA01184D

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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Figure 5. Package outline note WLCSP56 (SOT1914-1)

4 Legal information

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